

In the Abstract:

ABSTRACT OF THE DISCLOSURE

~~Surface-mountable miniature luminescent diode and/or photodiode and method for its production~~

~~In the case of a~~ A surface-mountable miniature luminescent diode with a chip package which has a leadframe (16) and a semiconductor chip (22) which is arranged on the leadframe (16) and is in electrical contact with it and which contains an active, radiation-emitting region, according to the invention the ~~. The~~ leadframe (16) is formed by a flexible multi-layered sheet (12, 14).

Figure 1